

formed to direct light emitted from said light emitting diode element to said fluorescent material containing layer and said resin seal member, whereby light emerging from the light emitting diode element into the fluorescent material containing layer is converted in wavelength by the fluorescent material in the fluorescent material containing layer;

wherein the light which has been converted in wavelength is blended with light directed from the light emitting diode element to the resin seal member.

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27. (New) A light emitting diode comprising:

a. a base;

b. two or more light emitting diode elements mounted on the base wherein at least one of said two or more light emitting diode elements is a light emitting diode element for blue luminescence made of a gallium nitride type compound semiconductor or a silicon carbide type compound semiconductor;

c. a resin seal member for protecting each surface side of the light emitting diode elements;

d. a fluorescent material containing layer which contains a fluorescent material and which is arranged on a back side of the light emitting diode element for blue luminescence;

whereby light emitted from the light emitting diode element for blue luminescence into the fluorescent material containing layer is converted in wavelength by the fluorescent material in the fluorescent material containing layer; and

the light which has been converted in wavelength is blended with light directed from the light emitting diode element to the resin seal member.

Please amend claim 2 as follows:

2. (Amended) The light emitting diode according to claim 26, wherein said light emitting diode element is a light emitting diode for blue luminescence, made of gallium nitride type compound semiconductor or SIC type compound semiconductor.

Please amend claim 4 as follows:

4. (Amended) The light emitting diode according to claim 26, wherein said fluorescent material containing layer is composed of a fluorescent material dispersed into an adhesive; and a back of said light emitting diode element is firmly fixed to said base by the adhesive action of said fluorescent material containing layer.

[Please amend claim 5 as follows:]

5. (Amended) The light emitting diode according to claim 26, wherein said fluorescent material containing layer is formed with a fluorescent material and an adhesive separate from each other; and a fluorescent material containing resin layer and an adhesive layer are formed in layers on a top surface of said base.

[Please amend claim 6 as follows:]

6. (Amended) The light emitting diode according to claim 4, wherein said fluorescent material containing layer is formed on the top surface of said base by printing means.

[Please amend claim 7 as follows:]

7. (Amended) The light emitting diode according to claim 26, wherein said fluorescent material containing layer is a fluorescent material containing resin sheet pasted on a top surface of said base.

[Please amend claim 8 as follows:]

8. (Amended) The light emitting diode according to claim 4, wherein said fluorescent material is an yttrium compound.

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[Please amend claim 9 as follows:]

9. (Amended) The light emitting diode according to claim 26, wherein a periphery of said fluorescent material containing layer is surrounded by a dam provided on a top surface of said base.

[Please amend claim 10 as follows:]

10. (Amended) The light emitting diode according to claim 26, wherein a reflecting surface is arranged on a bottom side of said fluorescent material containing layer or a top surface of said base.

[Please amend claim 11 as follows:]

11. (Amended) The light emitting diode according to claim 26, wherein an upward reflecting surface tilting outward is arranged around said light emitting diode elements.

[Please amend claim 12 as follows:]

12. (Amended) The light emitting diode according to claim 26, wherein a lens portion of convex shape is formed on a top side of said resin seal member.

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[Please amend claim 13 as follows:]

13. (Amended) The light emitting diode according to claim 26, wherein said resin seal member is formed flat at a top side; and a fluorescent material containing layer is formed on the top side.

[Please amend claim 14 as follows:]

14. (Amended) The light emitting diode according to claim 26, wherein said base is a glass epoxy substrate, a solid-molded substrate of liquid crystal polymer, or a sheet metal substrate.

[Please amend claim 15 as follows:]

15. (Amended) The light emitting diode according to claim 26, wherein said light emitting diode element is connected to a pair of electrodes arranged on said base; and said electrodes are surface-mounted directly to printed wires on a motherboard.

[Please amend claim 16 as follows:]

16. (Amended) The light emitting diode according to claim 27, wherein said fluorescent material containing layer is composed of a fluorescent material dispersed into an adhesive; and a back of said light emitting diode element is firmly fixed to said base by

the adhesive action of said fluorescent material
containing layer.

[Please amend claim 17 as follows:]

17. (Amended) The light emitting diode
according to claim 27, wherein said fluorescent material
containing layer is formed with a fluorescent material
and an adhesive separate from each other; and a
fluorescent material containing resin layer and an
adhesive layer are formed in layers on a top surface of
said base.

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[Please amend claim 18 as follows:]

18. (Amended) The light emitting diode
according to claim 27, wherein said fluorescent material
containing layer is a fluorescent material containing
resin sheet pasted on a top surface of said base.

[Please amend claim 19 as follows:]

19. (Amended) The light emitting diode
according to claim 27, wherein a periphery of said
fluorescent material containing layer is surrounded by a
dam provided on a top surface of said base.

[Please amend claim 20 as follows:]

20. (Amended) The light emitting diode according to claim 27, wherein a reflecting surface is arranged on a bottom side of said fluorescent material containing layer or a top surface of said base.

[Please amend claim 21 as follows:]

21. (Amended) The light emitting diode according to claim 27, wherein an upward reflecting surface tilting outward is arranged around said light emitting diode elements.

[Please amend claim 22 as follows:]

22. (Amended) The light emitting diode according to claim 27, wherein a lens portion of convex shape is formed on a top side of said resin seal member.

[Please amend claim 23 as follows:]

23. (Amended) The light emitting diode according to claim 27, wherein said resin seal member is formed flat at a top side; and a fluorescent material containing layer is formed on the top side.

[Please amend claim 24 as follows:]

24. (Amended) The light emitting diode according to claim 27, wherein said base is a glass epoxy

substrate, a solid-molded substrate of liquid crystal polymer, or a sheet metal substrate.

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[Please amend claim 25 as follows:]

25. (Amended) The light emitting diode according to claim 27, wherein said light emitting diode element is connected to a pair of electrodes arranged on said base; and said electrodes are surface-mounted directly to printed wires on a motherboard.
